

Electronic Patent Application Fee Transmittal

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|--|----------------------------------|-----------------|---------------|-----------------------------|
| Application Number: | 10807417 | | | |
| Filing Date: | 23-Mar-2004 | | | |
| Title of Invention: | Microcap wafer bonding apparatus | | | |
| First Named Inventor/Applicant Name: | R. Shane Fazzio | | | |
| Filer: | Thomas F. Woods | | | |
| Attorney Docket Number: | 10030899-1 | | | |
| Filed as Large Entity | | | | |
| Utility under 35 USC 111(a) Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Notice of appeal | 1401 | 1 | 540 | 540 |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|-------------------|----------|----------|--------|----------------------|
| Miscellaneous: | | | | |
| Total in USD (\$) | | | | 540 |